

2SB1407(L)/(S)

Silicon PNP Epitaxial

HITACHI

ADE-208-876 (Z)

1st. Edition

Sep. 2000

Application

Low frequency power amplifier complementary Pair with 2SD2121(L)/(S)

Outline

DPAK



S Type



L Type

- 1. Base
- 2. Collector
- 3. Emitter
- 4. Collector

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	−35	V
Collector to emitter voltage	V_{CEO}	−35	V
Emitter to base voltage	V_{EBO}	−5	V
Collector current	I_C	−2.5	A
Collector peak current	$I_{C(peak)}$	−3	A
Collector power dissipation	P_C^{*1}	18	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	−55 to +150	°C

Note: 1. Value at $T_C = 25^{\circ}\text{C}$.

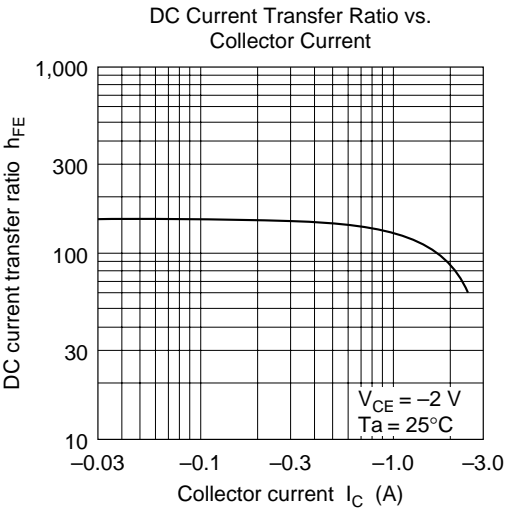
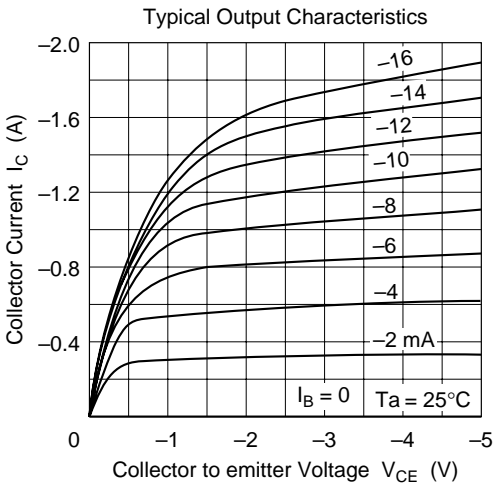
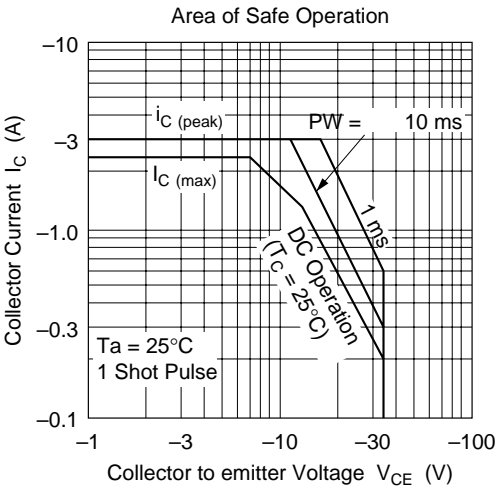
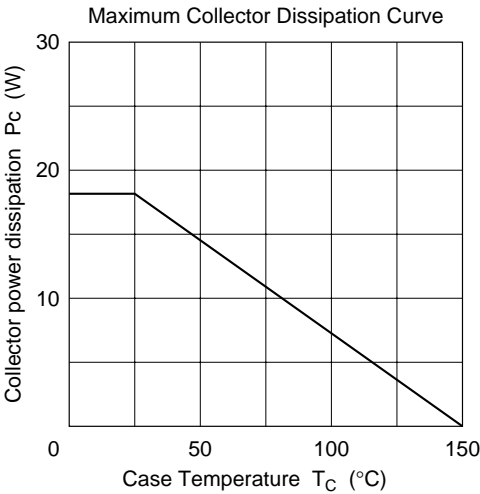
Electrical Characteristics (Ta = 25°C)

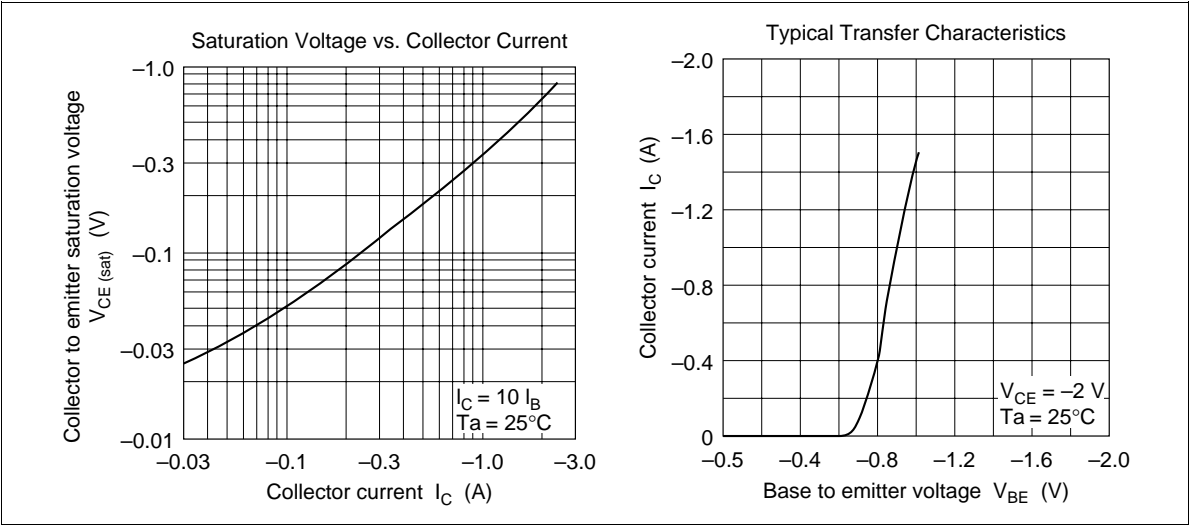
Item	Symbol	Min	Typ	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	−35	—	—	V	$I_C = -1\text{ mA}$, $I_E = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	−35	—	—	V	$I_C = -10\text{ mA}$, $R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	−5	—	—	V	$I_E = -1\text{ mA}$, $I_C = 0$
Collector cutoff current	I_{CBO}	—	—	−20	μA	$V_{CB} = -35\text{ V}$, $I_E = 0$
DC current transfer ratio	h_{FE1}^{*1}	60	—	320		$V_{CE} = -2\text{ V}$, $I_C = -0.5\text{ A}^{*2}$
	h_{FE2}	20	—	—		$V_{CE} = -2\text{ V}$, $I_C = -1.5\text{ A}^{*2}$
Base to emitter voltage	V_{BE}	—	—	−1.5	V	$V_{CE} = -2\text{ V}$, $I_C = -1.5\text{ A}^{*2}$
Collector to emitter saturation voltage	$V_{CE(sat)}$	—	—	−1.0	V	$I_C = -2\text{ A}$, $I_B = -0.2\text{ A}^{*2}$

Notes: 1. The 2SB1407(L)/(S) is grouped by h_{FE1} as follows.

B	C	D
60 to 120	100 to 200	160 to 320

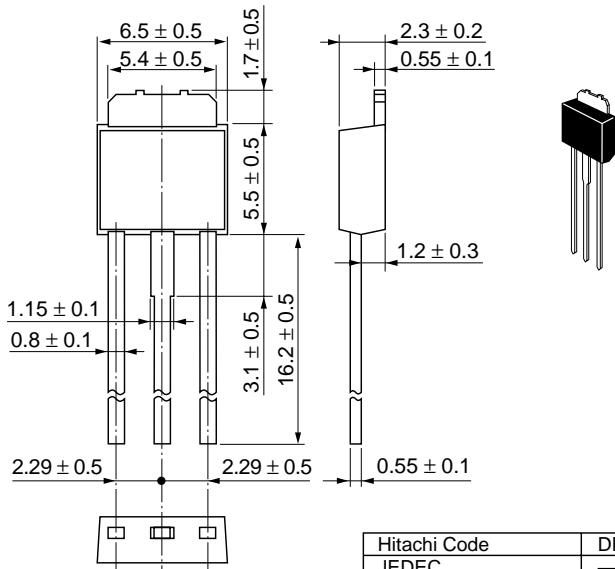
2. Pulse test.





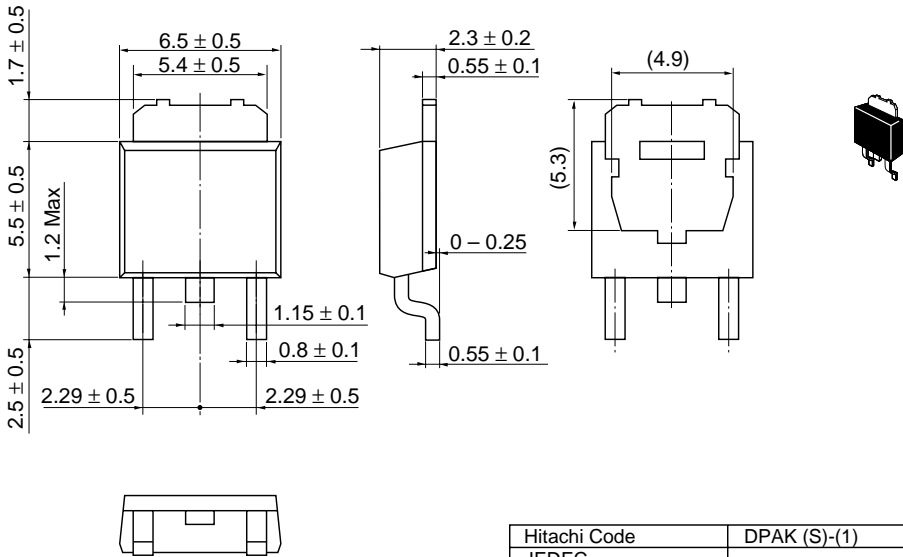
Package Dimensions

Unit: mm



Hitachi Code	DPAK (L)-(1)
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.42 g

Unit: mm



Hitachi Code	DPAK (S)-(1)
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.28 g

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